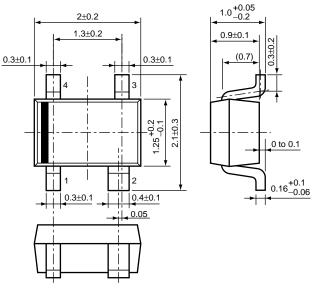
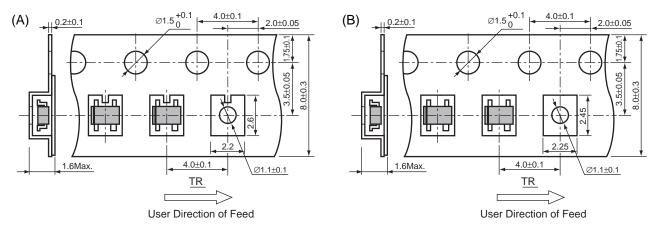
• SC-82AB

PACKAGE DIMENSIONS

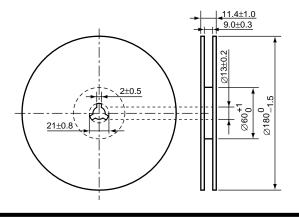


TAPING SPECIFICATION *Using both (A) and (B)



TAPING REEL DIMENSIONS (EIAJ-RRM-08Bc)

(1reel=3,000pcs)



Nisshinbo Micro Devices Inc.

PE-SC-82AB-101019

Unit: mm

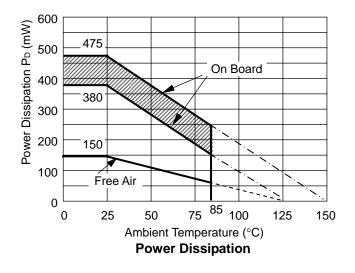
PACKAGE INFORMATION

POWER DISSIPATION (SC-82AB)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

	Standard Land Pattern	
Environment	Mounting on Board (Wind velocity=0m/s)	
Board Material	Glass cloth epoxy plastic (Double sided)	
Board Dimensions	40mm × 40mm × 1.6mm	
Copper Ratio	Ratio Top side : Approx. 50% , Back side : Approx. 50%	
Through-holes	φ0.5mm × 44pcs	

Measurement Results	(Topt=25°C, Tjmax=125°C)		
	Standard Land Pattern	Free Air	
Power Dissipation	380mW	150mW	
Thermal Resistance	θja=(125–25°C)/0.38W=263°C/W	θja=(125–25°C)/0.15W=667°C/W	
		θjc=60°C/W	

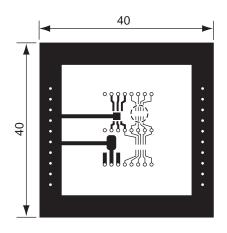


The above graph shows the Power Dissipation of the package based on Tjmax=125°C and Tjmax=150°C. Operating the IC in the shaded area in the graph might have an influence it's lifetime.

Operating time must be within the time limit described in the table below, in case of operating in the shaded area.

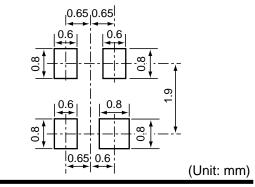
Product Name		Operating time	Estimated years*
RP103Q	RP104Q	9,000hrs	6 years

*The volume is calculated on the supposition that operating four hours/day.



Measurement Board Pattern

RECOMMENDED LAND PATTERN



Nisshinbo Micro Devices Inc.